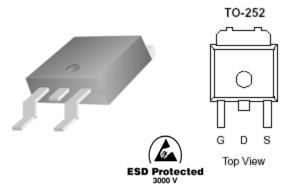
## N-Channel 40-V (D-S) MOSFET

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low  $r_{DS(on)}$  and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

V <sub>DS</sub> (V)	$r_{DS(on)} m(\Omega)$	<b>I</b> <sub>D</sub> (A)
40	$32 @ V_{GS} = 10V$	33
40	$42 @ V_{GS} = 4.5V$	29

- Low  $r_{DS(on)}$  provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe DPAK saves board space
- Fast switching speed
- High performance trench technology



PRODUCT SUMMARY

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C UNLESS OTHERWISE NOTED)					
Parameter	Symbol	Limit	Units		
Drain-Source Voltage			40	V	
Gate-Source Voltage	<sup>7</sup> oltage				
Continuous Drain Current <sup>a</sup>	$T_C=25^{\circ}C$	$I_D$	33	A	
Pulsed Drain Current <sup>b</sup>			40	A	
Continuous Source Current (Diode Conduction) <sup>a</sup>	$I_S$	30	A		
Power Dissipation <sup>a</sup>	$T_C=25^{\circ}C$	$P_{D}$	50.0	W	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Maximum	Units		
Maximum Junction-to-Ambient <sup>a</sup>	$R_{ heta JA}$	50	°C/W		
Maximum Junction-to-Case	$R_{ heta JC}$	3.0	°C/W		

### Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

1

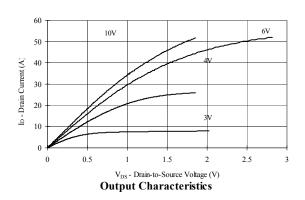
Parameter	Symbol Test Conditions	Limits			Unit	
r ar ameter	Symbol Test Conditions		Min	Typ	Max	UIII
Static						
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \text{ uA}$	1			V
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}, V_{GS} = 20 \text{ V}$			±100	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^{\circ}\text{C}$			25	uA
On-State Drain Current <sup>A</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	34		23	A
Drain-Source On-Resistance <sup>A</sup>	r <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, I_D = 33 \text{ A}$ $V_{GS} = 4.5 \text{ V}, I_D = 29 \text{ A}$			32 42	mΩ
Forward Tranconductance <sup>A</sup>	$g_{ m fs}$	$V_{DS} = 15 \text{ V}, I_D = 33 \text{ A}$		22		S
Diode Forward Voltage	$V_{\mathrm{SD}}$	$I_S = 34 \text{ A}, V_{GS} = 0 \text{ V}$		1.1		V
Pulsed Source Current (Body Diode) <sup>A</sup>	$I_{SM}$			5		Α
Dynamic <sup>b</sup>						
Total Gate Charge	$Q_{g}$	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V},$		5		
Gate-Source Charge	$Q_{gs}$	$I_{D} = 33 \text{ A}$		1.1		nC
Gate-Drain Charge	$Q_{gd}$	тр 33 и		1.4		
Input Capacitance	$C_{iss}$	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$		489		рF
Output Capacitance	$C_{oss}$	f = 1 MHz		94		þr.
Turn-On Delay Time	$t_{d(on)}$			16		
Rise Time	$t_{\rm r}$	$V_{DD}$ = 25 V, $R_L$ = 25 $\Omega$ , $I_D$ = 34 A,		5		nS
Turn-Off Delay Time	$t_{d(off)}$	$V_{GEN} = 10 \text{ V}$		23		113
Fall-Time	$t_{\mathrm{f}}$			3		

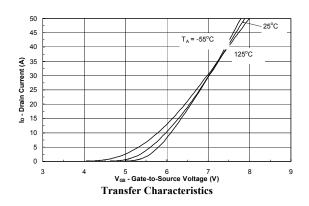
#### Notes

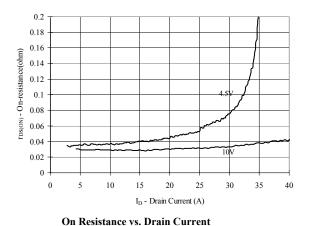
- a. Pulse test:  $PW \le 300us duty cycle \le 2\%$ .
- b. Guaranteed by design, not subject to production testing.

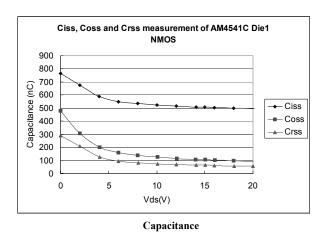
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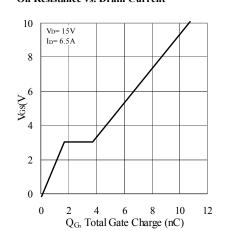
## Typical Electrical Characteristics



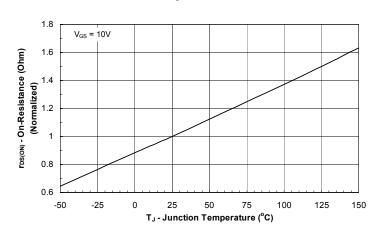






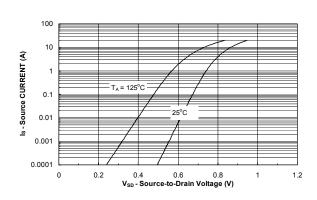


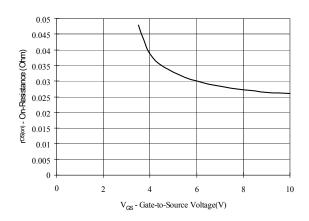
**Gate Charge** 



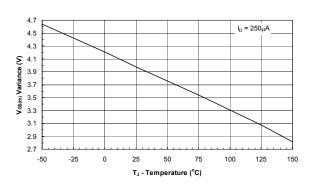
On-Resistance vs. Junction Temperature

## Typical Electrical Characteristics

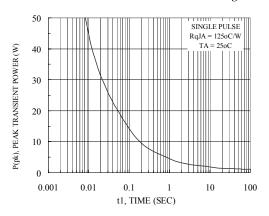




#### Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

Figure 10. Single Pulse Maximum Power Dissipation



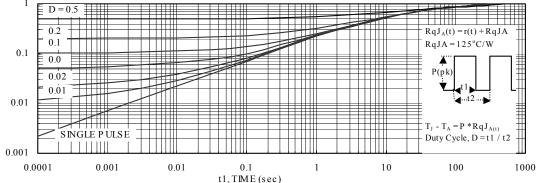
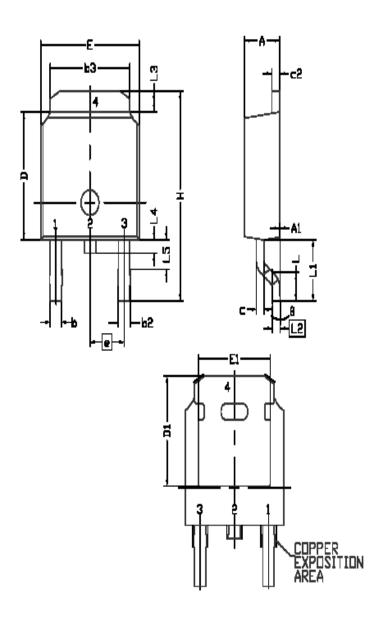


Figure 11. Transient Thermal Response Curve

# Package Information



CHADE	DIMENS:	iinal i	REGMTS		
LOGMY2	MIN	Ž	MAX		
Ε	6.40	6.60	6,731		
L	1.40	1.52	1.77		
L1	2.743 REF				
L2		.508 BS	ñ		
L3	0.89	1	1.27		
L4	0.64		턤		
15	1	١	-		
D	6.00	6.10	6'553		
H	9.40	10,00	10.40		
٩	0.64	0.76	0.88		
P5	0.77	0.84	1.14		
ь3	5.21	5.34	5.46		
٠		286 BS	3		
A	2.20	2.30	5'38		
A1	0		0.127		
u	0.45	0.50	0.60		
-52	0.45	0.50	0.58		
М	5.30		-		
c	4.40		I		
8	ò	1	10*		